

Serial No. 10/779,658

Attorney Docket No. 01-559

LISTING OF CLAIMS:

1. (Currently amended) A semiconductor pressure sensor device comprising:
 - a conductive member;
 - a sensor chip for detecting a pressure and generating an electrical signal corresponding to the pressure;
 - a bonding pad that is formed of an aluminum base material and provided on a surface of the sensor chip;
 - a bonding wire electrically connecting the sensor chip and the conductive member; and
 - a protective member having characteristics of electric insulation and plasticity and covering the sensor chip and the bonding wire,
 - wherein the bonding wire is formed of an alloy of Au and Pd.
2. (Original) The pressure sensor device of Claim 1,
 - wherein a diameter of the bonding wire is not larger than 40 μm .
3. (Original) The pressure sensor device of Claim 1, further comprising:
 - a circuit chip for processing the electrical signal from the sensor chip; and
 - an additional bonding wire electrically connecting the circuit chip and the sensor chip,
 - wherein the protective member covers the circuit sensor chip and the bonding wire, and
 - wherein the additional bonding wire is formed of an alloy of Au and Pd.

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4. (Original) The pressure sensor device of Claim 3,
wherein a diameter of the additional bonding wire is not larger than 40 μm .

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